CALL FOR PAPERS
September 11–13, 2024 in Berlin

IEEE ESTC 2024

Executive Committee:

General Chair:
T. Braun, Fraunhofer IZM, DE

Program Chair:
T. Mattila, Business Finland, FI

Exhibition & Sponsors Manager:
S. Kröhnert, ESPAT-Consulting, DE

Treasurer:
T. Zerna, Technical University Dresden, DE

Event Manager:
M. Creutzfeldt, mcc Agentur für Kommunikation GmbH, DE

Sponsors

IEEE ELECTRONICS PACKAGING SOCIETY

IEEE

iMAPS

The IEEE Electronics System-Integration Technology Conference (IEEE ESTC) is the premier international event in the field of electronics packaging and system integration. The conference is organized every two years in Europe and is supported by IEEE-EPS in association with IMAPS-Europe. The 10th ESTC will be taking place in Berlin, the capital of Germany.

The IEEE ESTC 2024 seeks original, noncommercial papers describing research and innovations in all areas of electronics packaging and system integration. Authors are invited to submit a **500-word abstract with up to two figures** describing recent work. Abstracts must detail the objectives of the work presented and demonstrate new results.

CONFERENCE TOPICS:

- Advanced Packaging
- Materials for Interconnects and Packaging
- Optoelectronic Systems Packaging
- Assembly and Manufacturing Technologies

- Design Tools and Modeling
- Power Electronics System Packaging
- Advanced Technologies for Emerging Systems
- Reliability of Electronic Devices and Systems
- Flexible, Printed and Hybrid Electronics
- RF, mm-wave and THz Systems Packaging

The technical program will include oral talks, poster presentations, an exhibition, special sessions and invited keynote talks given by renowned speakers.

Proceedings
Accepted contributions will be published in the conference proceedings, and archived in IEEE Xplore (provided they comply with specifications). ESTC papers can be searched through IEEE, Google Scholar and other search engines.

Sponsors and exhibitors welcome!
The IEEE ESTC 2024 offers attractive packages for sponsors and exhibitors! Please contact local committee for further details: exhibition@estc-conference.net.

ESTC Student Travel Award
The student travel grant program for IEEE ESTC awards up to 6 grants. The competition is open to all full-time graduate students enrolled at an accredited institution in a program of study within the scope of IEEE ESTC. The student must be listed as the primary author on the abstract.

Please check the Conference website for details on hotel bookings and travel arrangements.

Important dates:
Conference: 11 – 13 September 2024
Abstract submission opens: 1 December 2023
Abstract submission deadline: 1 March 2024
Paper submission deadline: 31 May 2024
Notification of acceptance: 5 April 2024

ABSTRACT SUBMISSION

Please submit your abstract of 500 words + two figures (optional) at

https://www.conftool.net/estc2024

VENUE
MOA Berlin
Stephanstraße 41
10559 Berlin

CONTACT
Local Conference Committee
Email: office@estc-conference.net
Website: https://www.estc-conference.net/